

SLSD-71N500

92.1mm² Solderable Chip Silicon Photodiode with Wire

The SLSD-71N500 is large 9.8x9.4mm active area solderable Silicon photodiode with wire. The device offers linear short circuit current over a wide range of optical power with high reliability. It is suited for power conversion applications due to their low internal impedance, relatively high shunt impedance, and stability. It is a reliable detector for instrumentation and light beam sensing applications.

Applications	Features		
Light Sensing	With 152mm Long Leads		
Power Generation	Visible to IR		
	Low capacitance		
	92.1mm² Active Area		





Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	
Reverse Voltage	V _R	-	20	V	
Operating Temperature	T _{OP}	-40	+105	°C	
Storage Temperature	T _{STG}	-40	+105	°C	

Package Wire on Die

Typical Electro-Optical Specifications at T_A=23 °C

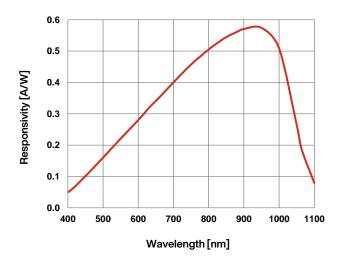
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Active Area	-	A.A.	-	92.1	-	mm²
Active Area Dimensions	-	A.A. _D	-	9.8x9.4	-	mm
Spectral Range	Spot Scan	Δλ	400	-	1100	nm
Peak Wavelength	λ=Peak	λ_{Peak}	-	950	-	nm
Acceptance Half Angle	(off center line)	V_{RBD}	-	60	-	deg
Short Circuit Current	V _R =0V, Ee=25mW/cm ² **	I _{sc}	2.5	4.0	-	mA
Open Circuit Voltage	Ee=25mW/cm ^{2**}	V _{oc}	-	0.40	-	V
Breakdown Voltage	$I_R = 100 \mu A$	T_{F}	20	-	-	V
Responsivity	λ =950nm, Flood illumination*	R_{λ}	-	0.57	-	A/W
Capacitance	$V_{_{\rm R}}$ =0V, Ee=0, f=1MHz	C	-	2.0	-	nF
Dark Current	V _R =5V, Ee=0, T=25°C	I _{RD}	-	-	1.7	μΑ

^{*}Minimum of 50% of active area illuminated **Light source@ 2854K

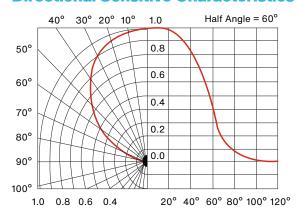




Typical Spectral Response

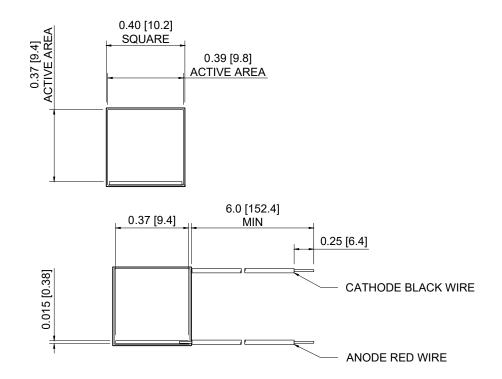


Directional Sensitive Characteristics



Mechanical Specifications

Units are in inches [mm]





General Care and Handling Instructions

Photodiodes:

Handling and Storage

- Handle Photodiodes gently to prevent damage.
- Avoid exposing Photodiodes to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

 Gently clean the glass (borosilicate or quartz window) using a 50/50 mixture of Methanol and isopropyl alcohol and a soft, optical-grade pad.

$Special \, Considerations \, for \, Plastic \, or \, Epoxy \, Encapsulated \, Photodiodes$

- Protect from intense light sources such as direct sunlight.
- Avoid exposure to harsh chemicals like THINNERS, ACETONE, and TRICHLOROETHYLENE.
- Cleaning with a 50/50 mixture of Methanol and isopropyl alcohol (IPA) is recommended. Cleaning in an ultrasonic bath is generally not recommended.

CdS Photocells:

Handling and Storage

- Handle CdS Photocells gently to prevent damage.
- Avoid exposing CdS Photocells to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

- Gently clean the glass or plastic covering using a 50/50
- mixture of Methanol and isopropyl alcohol and a soft, opticalgrade pad.

Special Considerations

 DO NOT use Vapor Phase Soldering or Reflow Soldering for CdS components.

Optocouplers and LEDs:

Handling and Storage

- Handle Optocouplers and LEDs gently to prevent damage.
- Avoid exposing the devices to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

Cleaning

 For plastic molded devices, cleaning with a 50/50 mixture of Methanol and isopropyl alcohol is recommended. Cleaning in an ultrasonic bath is generally not recommended.

Special Considerations

 Avoid exposing plastic molded devices or epoxy glob top devices to harsh chemicals like THINNERS, ACETONE, and TRICHLOROETHYLENE.

Legal Disclaimer

Information in this data sheet is believed to be correct and reliable. However, no responsibility is assumed for possible inaccuracies or omission. Specifications are subject to change without notice.



Most of our standard catalog products are RoHS Compliant. Please contact us for details.

Electrostatic Discharge (ESD) Sensitivity:

 All devices are considered ESD-sensitive. They are shipped in ESD protective packaging. When unpacking and using these products, anti-ESD precautions should be observed.

Lead Trimming and Bending:

 Standard lead trimming after soldering is an acceptable practice; however, do not attempt to bend or modify the leads incorrectly, as it can damage the glass feed-through or the plastic encapsulant.

Soldering Instructions:

- Use a soldering iron with a tip temperature of 300°C max.
- Consult with your preferred solder manufacturer to determine a solder alloy and flux combination, as well as the reflow profile appropriate for your application.

General Precautions for all Devices

1. Moisture Prevention:

Ensure devices are stored in a dry environment to prevent moisture ingress, which can cause damage during soldering. Refer to J-STD-20 for guidance on proper baking procedures to prevent moisture related damage.

2. Lead Splaying:

If required, carefully splay the leads of the devices according to the specific application needs. Be cautious when splaying leads, as improper techniques may damage the device. Consult technical support or device datasheets for guidance on lead splaying.

3. Mechanical Stress:

Handle devices with care throughout the installation process to prevent damage.

4. Circuit Protection and Layout:

Optimize the circuit design and layout to ensure proper functioning and prevent damage to the devices. Include appropriate protection measures like ESD protection diodes, current-limiting resistors, and voltage regulation.

5. After-Sale Support:

For troubleshooting and device-specific inquiries, please consult with our technical support team. They can offer valuable guidance and suggestions on handling, operation, and application-related questions. To reach them, please contact the Advanced Photonix Applications group at Techsupport@advancedphotonix.com.

